## ABSTRACT OF THE DISCLOSURE

An efficient fabrication method of a SON type semiconductor device is to be provided. A plurality of linear leadframes is arranged side by side separately from each other. A plurality of semiconductor chips with a plurality of electrode pads is mounted over the plurality of the linear leadframes separately in the direction of extending the linear leadframes. The plurality of the electrode pads is joined to the plurality of the linear leadframes with bonding wires. An encapsulation part for encapsulating the semiconductor chip and the bonding wires and an interframe encapsulation part for burying a space between the linear leadframes exposed outside the encapsulation part are formed. A groove part for cutting all the linear leadframes placed right under the semiconductor chip in the vertical direction to the direction of extending the linear leadframes is formed. The leadframes and the interframe encapsulation parts exposed between the plurality of the semiconductor chips are cut to separate into a semiconductor device.